Page 9, delete lines 1-16; and

line 17, whange "[Best Mode for Carrying Out the Invention]" to

DETAILED DESCRIPTION OF PREFERRED EMBODIMENTS

Page 32, Jine 21, change "22" to --1422--; and

line 27, change "21" to --1421--.

Page 34, line 1, change "20" to --18--.

IN THE CLAIMS:

Please amend claims 1-16 as follows:

1. (Amended) A thin film transistor including [on the surface side of a substrate] a plurality of component parts comprising:

a channel region; [opposed to]

a gate electrode opposed to the channel region;[, with]

a gate insulating film provided [the ebetween, and] between the channel region

and the gate electrode;

a source-drain region connected to said channel region[,and a thin film transistor having];

a source-drain wiring layer electrically connected to said source-drain region[,]; and

a gate wiring layer electrically connected to said gate electrode,

[in which] at least one of the component [part composed of] parts being formed from a conductive film or a semiconductor film[, among the component parts of each thin film transistor, is] and being provided with a radiating extension extending outwardly from the at least one component part.

Fig. B

- 2. (Amended) [Thin] The thin film [transistors] transistor according to Claim 1, heat dissipating wherein said radiating extension [is a portion extending] extends outwardly from both sides of said gate electrode [at both sides].
- 3. (Amended) [Thin] The thin film [transistors] transistor according to Claim 2, by dissipating wherein the [extending portion] adiating extension of said gate electrode is provided on at least one end of said gate electrode

Fig. 5 4. (Amended) [Thin thin film [transistors] transistor according to Claim 3, heat dissipation wherein said gate wiring layer is electrically connected to the [extending portion] radiating extension of said gate electrode by a plurality of contact holes.

wherein the [extending portion] radiating extension of said gate electrode is provided in a [region where the extending portion of said gate electrode is] position opposed to said channel region.

[Thin] The thin film [transistors] transistor according to Claim 5, wherein the [extending portion] radiating extension of said gate electrode is provided at a location corresponding to an approximately central region of [the width of] said channel region.

7. (Amended) [Thin] The thin film [transistors] transistors according to Claim 1, wherein said radiating extension [is a portion extending] extends from both sides of said channel region [to both sides].

8. (Amended) [Thin] The thin film [transistors] transistor according to Claim 7, heat dissipation of said channel region is provided in a [region] position opposed to said gate electrode.

9. (Amended) [Thin] The thin film [transistors] transistor according to Claim 7, wherein said radiating extension [is a portion extending] extends from both sides of said source-drain region [to at both sides].

10. (Amended) [Thin] The thin film [transistors] transistor according to Claim 9, wherein said source-drain wiring layer is electrically connected to the [extending portion] heat disting extension of said source-drain region by a plurality of contact holes.

transistors according to Claim 1, wherein said radiating extension [is an extending portion extended] extends from both sides of said source-drain region [at both sides so that, in a CMOS inverter circuit including], said thin film transistors[,which are] having an [inversely conductive] inverse conductivity type from each other, [the] adjacent source-drain regions of said thin film transistors [are] being connected [between CMOS circuits].

- 12. (Amended) [Thin film transistors] The CMOS inverter circuit according to List pating

 Claim 11, wherein said radiating extension is provided with a conductivity by using an impurity identical to [the] an impurity of said source-drain region to which said radiating extension [itself] is connected.
- 13. (Amended) [Thin film transistors] The CMOS inverter circuit according to head disciplified.

 Claim 11 [or 12], wherein said radiating extension is formed in a region opposed to said source-drain wiring layer [for], said source-drain wiring layer connecting the adjacent source-drain regions of said thin film transistors [between the CMOS circuits].
- 14. (Amended) [Thin] The thin film [transistors] transistor according to claim 1, but Lissifating wherein said radiating extension [is an extending portion] extends from both sides of at least [either] one of said source-drain wiring layer and said gate wiring layer [at both sides].
 - 15. (Amended) A liquid crystal display device [using] <u>comprising</u> an active matrix substrate on which a driving circuit including a thin film transistor as defined in [any of Claims] <u>Claim</u> 1 [to 14] is formed.
 - 16. (Amended) An electronic apparatus [in which] comprising a liquid crystal display device as defined in Claim 15 [is used].

-4-

- --18. A liquid crystal display device comprising an active matrix substrate on which a driving circuit including a CMOS inverter circuit as defined in Claim 11 is formed.--
- --19. An electronic apparatus comprising a CMOS inverter circuit as defined in Claim 11.--
- --20. The liquid crystal display device according to Claim 18, said plurality of heet dissipating component parts each extending in a longitudinal direction, the radiating extension extending in a direction substantially perpendicular to the longitudinal direction.--
- --21. The electronic apparatus according to Claim 19, said plurality of component heat dissipations parts each extending in a longitudinal direction, the radiating extension extending in a direction substantially perpendicular to the longitudinal direction.--

B

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